

ABSTRACT OF THE DISCLOSURE

A process of packaging an OEL panel is disclosed. A printed circuit board is provided, wherein the printed circuit board comprises a plurality of bonding pads and a plurality of bumps on the bonding pads. Next, at least one OEL panel having a plurality
5 of polysolder interconnections is provided. Next, the OEL panel disposed on the printed circuit board. A reflow process is performed so that the OEL panel can electrically connect with the PCB by the polysolder interconnections. Because of the low-temperature reflow process, the process of packaging an OEL panel can be accomplished by a low temperature process.

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